

## **REMARKS**

Claims 1-11 and 14 are now pending in the application. Claims 1, 2, 4-5, 8, and 10 are amended herein. Claims 12-13 are cancelled herein. Claim 14 is added herein. The Examiner is respectfully requested to reconsider and withdraw the rejection in view of the amendments and remarks contained herein.

### **REJECTION UNDER 35 U.S.C. § 102**

Claims 1-11 stand rejected under 35 U.S.C. § 102(b) as being anticipated by Hanakawa et al. (U.S. Pub. No. 2002/0005928). This rejection is respectfully traversed.

Claims 1 and 5 call for an electro-optical device including a sealant bonding a first substrate and a second substrate together by extending on both a protection layer and a region of the first substrate where the protection layer is not formed. Applicants submit that Hanakawa et al. does not disclose an electro-optical device including a sealant extending on both a protection layer and a region of a substrate where the protection layer is not formed. For example, Hanakawa et al. discloses a liquid crystal panel 100 including a sealant 110 between front and back substrates 200, 300 that does not extend onto a planarization film 205 (which corresponds to a protection layer). See at least Figure 2 of the Hanakawa et al. reference. Accordingly, for at least these reasons, Applicants submit that claims 1 and 5 are not anticipated by Hanakawa et al.

Claims 2-4 and 6-9 all depend from one of claims 1 and 5 and, therefore, for at least the same reasons stated above with respect to claims 1 and 5, should also be patentable.

Claim 10 calls for an electro-optical device including a sealant having a first region embracing a conductive member and a second region with a thickness larger than the first region, the sealant bonding a first substrate and a second substrate together. Applicants submit that Hanakawa et al. does not disclose an electro-optical device including a sealant having first and second regions, the second region having thickness larger than the first region. For example, Hanakawa et al. discloses a liquid crystal panel 100 including a sealant 110 having a part embracing a conductive particle 114 and a remaining part that are the same thickness. See at least Figures 2 and 11 of the Hanakawa et al. reference. Accordingly, for at least these reasons, Applicants submit that claim 10 is not anticipated by Hanakawa et al.

Claim 11 depends from claim 10 and, therefore, for at least the same reasons, should also be patentable.

Applicants, therefore, respectfully request reconsideration and withdrawal of the rejection.

Additionally, new claim 14 is added herein to provide Applicants with a varied scope of protection. Favorable consideration of this claim is also respectfully requested.

#### CONCLUSION

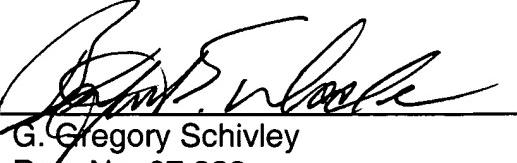
It is believed that all of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider and withdraw all presently outstanding rejections. It is believed that a full and complete response has been made to the outstanding Office Action and the present application is in condition for allowance. Thus, prompt and

favorable consideration of this amendment is respectfully requested. If the Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

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